**PART NUMBER(S):**
Please refer to Attachment A

**PCN / PCAN #:** 12-0913-02

**DATE:** 9/21/12

**PART DESCRIPTION:**
Please refer to [www.exar.com](http://www.exar.com)

**LEVEL OF CHANGE**
- **Level I, Customer Approval**
- **Level II, Customer Information**

**PRODUCT ATTRIBUTE AFFECTED**
- **Material Change**
- **Design Change**
- **Process Change**
- **Data Sheet Change**
- **Package Change**
- **Packing / Shipping**
- **Other, Explain:** New Assembly Supplier

**DESCRIPTION OF THE PROPOSED CHANGE**
Exar has qualified Cirtek, Philippines for 20 leads WSOIC and PDIP packages to replace the existing assembly supplier, CEI, Thailand.

Moisture sensitivity rating for WSOIC package will remain at MSL3 but the recommended reflow temperature is reduced from 260°C to 245°C.

There will be no change to Form, Fit or Function per the applicable datasheets.

**REASON FOR CHANGE**
CEI, Thailand has been damaged due to the flooding and it is out of business.

**DATE OF SAMPLES AVAILABLE**
Please verify timeliness for specific devices with customer support.

**DATE OF QUALIFICATION COMPLETED**
September 2012
<table>
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<tr>
<th>ESTIMATED CHANGE DATE OR DATE CODE</th>
<th>SUPPORTING DATA</th>
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</thead>
<tbody>
<tr>
<td>Upon customers approval.</td>
<td>Reliability data will be provided upon request.</td>
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</tbody>
</table>

PERSON TO CONTACT WITH QUESTIONS:

**LISA BEDARD**  
Exar Corporation  
1 Holiday Avenue  
West Tower, Suite 450  
Pointe-Claire, Quebec H9R 5N3  
Tel: (514) 429-1010 ext. 210  
Fax: (514) 695-2548  
Lisa.bedard@exar.com

Please acknowledge receipt of this PCN.

*Acknowledged:*

____________________________
Signature

____________________
Printed Name

____________________
Company

____________________
Title

____________________
Date

Approved [ ]  Not Approved [ ]  (Approved/Not Approved section not applicable and should be removed for all Level II PCNs)

Comments: ___________________________________________________________
## ATTACHMENT A

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<thead>
<tr>
<th>EXAR PRODUCTS</th>
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<tr>
<td>SP233ACT-L</td>
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